

### Express recovery diode Reverse Voltage50V-600v Forward current-1A

#### **Features**

Glass passivated chip
High surge current capability
Ldeal for surface mounted applications
Low power loss, high efficiency
Plastic Case Material has UL Flammability

#### Mechanical Data

Package: SMA

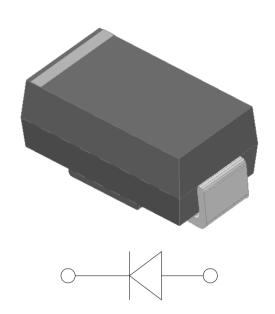
Terminals:Tin Plated leads, solderable per

Mil-STD-750 Method 2026

Polarity: As marked

Molding compound meets UL 94 V-0 flammability rating,

**ROHS-compliant** 



#### Maximum Ratings (Ta=25° Unless otherwise specified)

Tuno Number	CVMDOL	ES1					
Type Number	SYMBOL	Α	В	D	G	J	Umit
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	50	100	200	400	600	V
Maximum Average Forward Rectified Current	IO <sub>(AV)</sub>	1.0					Α
Peak Forward Surge Current 8.3ms Single half-sine-wave superimposed on rated load(JEDEC Method) on rated	IFSM _	25.0				А	
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25°C	II OW	50.0				Α	
Current squared time @1ms≤t8.3≤ms Tj=25℃,Rating of per diode	l <sup>2</sup> t	2.6			$A^2S$		
Maximum Forward Voltage at 1.0A DC	$V_{FM}$	0.95 1.3 1.7		1.7	V		
Maximum Reverse Current TA = $25^{\circ}$ C	IR -	5.0					uA
at Rated DC Blocking Voltage TA = 125℃	IK	100.0					
Maximum reverse recovery time	Trr	35.0			ns		
Typical Thermal Resistance Between junction and	$R_{QJa}$	65.0			°C/W		
Operating Junction Temperature Range	TJ	—55to+150				$^{\circ}$	
Storage Temperature Range	T <sub>STG</sub>		_	-55to+150	)		$^{\circ}$

FIG. 1MAXIMUM AVERAGE FORWARD CURRENT DERATING

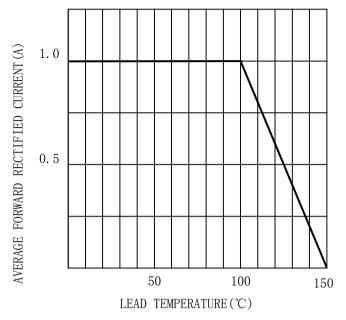


FIG. 2TYPICAL FORWARD CHARACTERISTICS

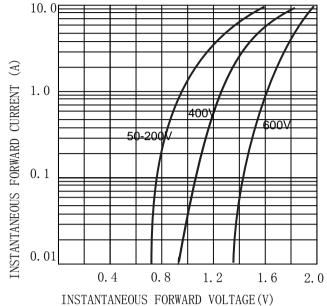


FIG. 3MAXIMUM NON-REPEITIVE SURGE CURRENT

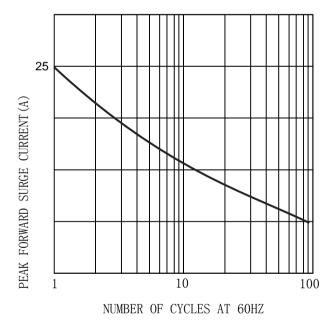
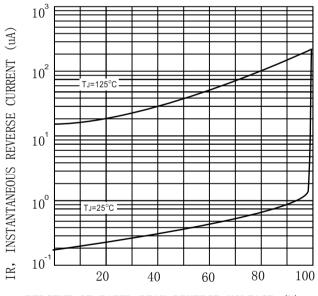


FIG. 4 TYPICAL REVERSE CHARACTERISTICS (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

### **MARKING INFORMATION**



= Logo

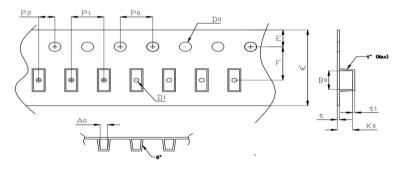
\*\*\*\* = Date Code Marking

ES1\* = Marking Code

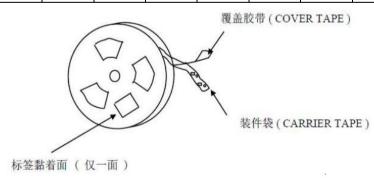
Print according to customer request

### **PACKING REQUIRMENTS**

Carrier tape packing



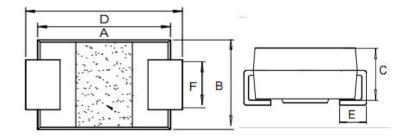
Specificati ons	Carrier tape type	Ao	Во	Ко	Ро	W	t	Exiplain
SMA	Anti-static	2.65± 0.10	5.20± 0.10	2.30± 0.10	4.00± 0.10	12.0± 0.10	0.20± 0.05	



	DEVICE	Tape		11"Reel		11"Reel		
TYPE	width	Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)	Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)	
	SMA	12mm	5000	20	100000	5000	18	90000

### Outline Dimensions

SMA



SMA								
DTM	INC	HES	MM					
DIM	MIN	MAX	MIN	MAX				
A	0. 16	0. 18	4.05	4.65				
В	0.09	0.11	2.4	2.8				
С	0.07	0.09	1.8	2. 3				
D	0. 18	0.21	4.67	5. 27				
Е	0.04	0.06	1	1.4				
F	0.05	0.06	1.2	1.6				



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